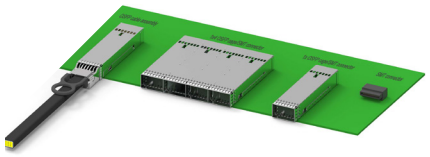
DATASHEET

OSFP 112 Gbps PAM-4 Interconnect System and Cable Assemblies ›

OSFP 112 Gbps PAM-4 Interconnect System and Cable Assemblies provide single-port, 8-lane I/O connectivity with DAC, AOC, ACC and optical modules for high-density switch applications.

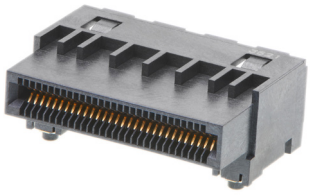


OSFP Interconnect System and Cable Assembly

FEATURES AND ADVANTAGES

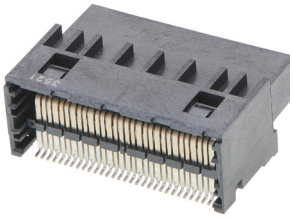
Connector

Supports 16 lanes of 112 Gbps PAM- 4; 4 Rx and 4 Tx pairs on each row
Provides an optimized interface



Compatible with previous-generation 56 Gbps mating interface
Is easy to implement without having to change entire infrastructure

Good contact points between ground shield and ground beams; good contact of the flex shield to rigid and ground beams
Prevents crosstalk



Laser welding technology used for terminal insertion
Ensures terminal position accuracy

Complete connector structure and mating interface
Provides grounding

Tight tolerance control of terminal width and spacing
Achieves superior signal integrity performance

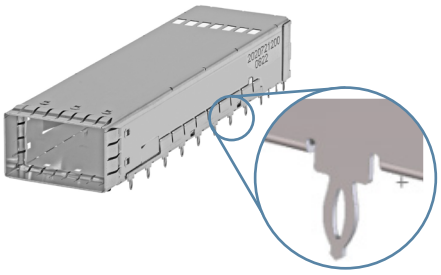
Cage

112 Gbps PAM-4 and 56 Gbps versions are available
Has a single-port, high-speed and high-density design intended to interface with DAC, AOC, ACC and optical modules

Meets IEEE 802.3ck channel compliance and OSFP 112G multi-source agreement (MSA)
Complies with industry standards for easy implementation

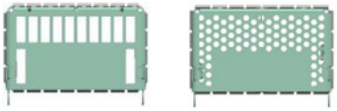
Single, dual and quad light pipe options available. Two different types of ventilation designs available
Provides design flexibility

Easy to insert cage to board while improving retention force
Delivers convenient assembly without sacrificing reliability



Improved EMI shielding and 2D press-fit design
Delivers enhanced EMI performance

Spring fingers
Offer additional robustness



MSA Suggested Design *Molex Design*

- **Hexagonal ventilation**
- **Thermally optimized for >12W applications**
- **Cooling to support a 25W module in an enterprise environment**

Enhances thermal and EMI performance

DATASHEET

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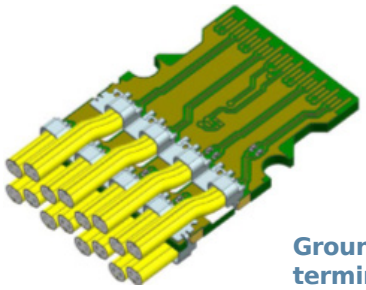
FEATURES AND ADVANTAGES

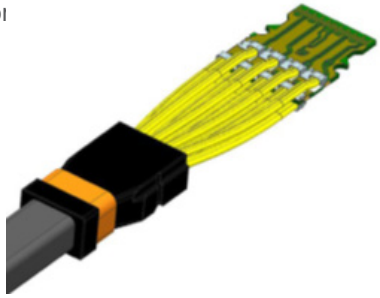
Direct Attach Cable (DAC) Assemblies



Ground structure terminates drain and prevents crosstalk
Improves signal integrity perfoı

MSA compatible for 56 and 112 Gbps applications
Delivers reliable high-speed performance

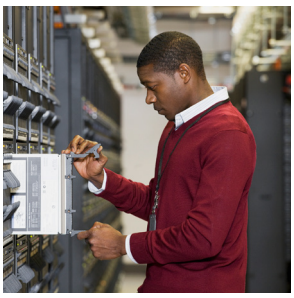
Molded cable strain relief inside backshell
Prevents wire and PCB damage



Supports up up to 2.0m DAC implementation. 25 to 26 AWG available
Offers design flexibility

MARKETS AND APPLICATIONS

Data Center Solutions
Telecommunication / Networking
High-density switches



High-density switches

www.molex.com/link/osfp.html

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